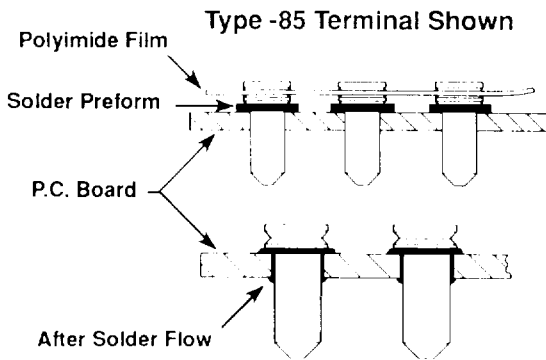
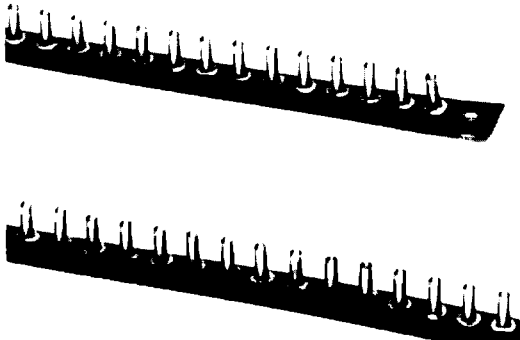


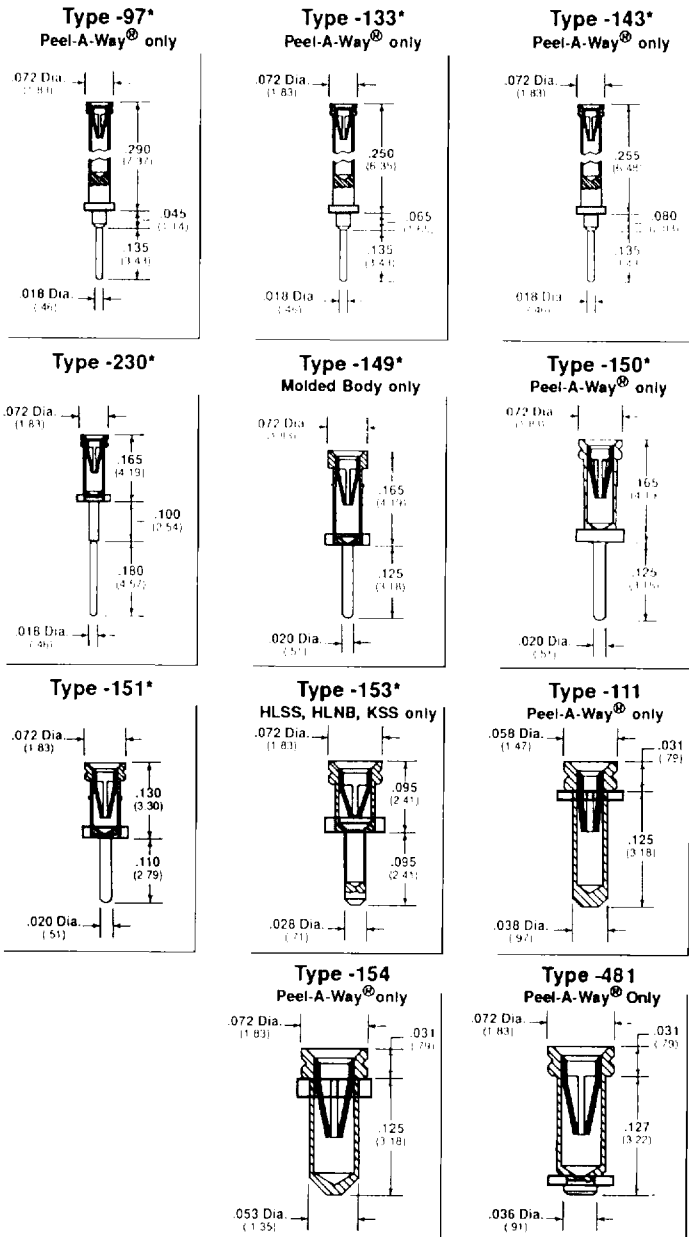
**Solder Preform SIP Sockets**



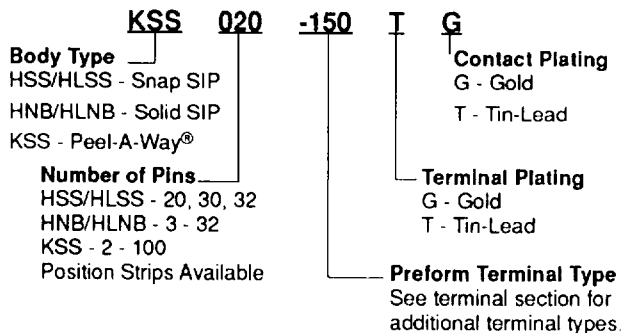
**Features:**

- Combines the labor of socket loading and solder application into one operation.
- Eliminates the use of solder paste and screening operation.
- Eliminates solder bridges and/or solder shorts due to excess solder.
- Insures a reliable solder joint with controlled solder volume.
- Ideal for Infrared or Vapor Phase applications.
- Available on a wide range of terminals.
- For custom solder preform terminal applications consult factory.
- See SIP pages 44 through 49 for material and dimensional information.
- Solder preforms 63% tin, 37% lead, RMA flux optional

**Terminal Information**



**How To Order**



Peel-A-Way® covered by patent rights issued and/or pending

\* Other patents pending.